



Advanced Power Electronics Corp.

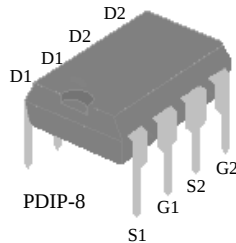
AP4513GD

Pb Free Plating Product

N AND P-CHANNEL ENHANCEMENT

MODE POWER MOSFET

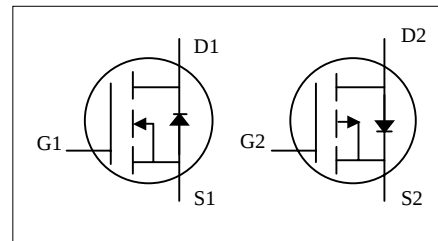
- ▼ Low Gate Charge
- ▼ Fast Switching Speed
- ▼ PDIP-8 Package
- ▼ RoHS Compliant



N-CH	BV_{DSS}	35V
	$R_{DS(ON)}$	36m Ω
	I_D	5.8A
P-CH	BV_{DSS}	-35V
	$R_{DS(ON)}$	68m Ω
	I_D	-4.3A

Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-channel	P-channel	
V_{DS}	Drain-Source Voltage	35	-35	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current ³	5.8	-4.3	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current ³	4.7	-3.4	A
I_{DM}	Pulsed Drain Current ¹	20	-20	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	2		W
	Linear Derating Factor	0.016		W/ $^\circ C$
E_{AS}	Single Pulse Avalanche Energy ⁴	12.5	12.5	mJ
I_{AR}	Avalanche Current	5	-5	A
E_{AR}	Repetitive Avalanche Energy ¹	0.05	0.05	mJ
T_{STG}	Storage Temperature Range	-55 to 150		$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150		$^\circ C$

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Thermal Resistance Junction-ambient ³	Max. 62.5	$^\circ C/W$



AP4513GD

N-CH Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	35	-	-	V
ΔBV _{DSS} /ΔT _j	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.03	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =5A	-	-	36	mΩ
		V _{GS} =4.5V, I _D =3A	-	-	60	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	-	3	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =5A	-	7	-	S
I _{DSS}	Drain-Source Leakage Current (T _j =25°C)	V _{DS} =30V, V _{GS} =0V	-	-	1	uA
	Drain-Source Leakage Current (T _j =70°C)	V _{DS} =24V, V _{GS} =0V	-	-	25	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V	-	-	±100	nA
Q _g	Total Gate Charge ²	I _D =5A	-	6	10	nC
Q _{gs}	Gate-Source Charge	V _{DS} =28V	-	2	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	3	-	nC
t _{d(on)}	Turn-on Delay Time ²	V _{DS} =15V	-	8	-	ns
t _r	Rise Time	I _D =1A	-	7	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω, V _{GS} =10V	-	16	-	ns
t _f	Fall Time	R _D =15Ω	-	3	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	470	750	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	90	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	60	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =1.7A, V _{GS} =0V	-	-	1.2	V
t _{rr}	Reverse Recovery Time	I _S =5A, V _{GS} =0V	-	17	-	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	11	-	nC

**P-CH Electrical Characteristics@T_j=25°C(unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-35	-	-	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C, $I_D=-1mA$	-	-0.03	-	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=-10V, I_D=-4A$	-	-	68	mΩ
		$V_{GS}=-4.5V, I_D=-2A$	-	-	100	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-	-3	V
g_{fs}	Forward Transconductance	$V_{DS}=-10V, I_D=-4A$	-	6	-	S
I_{DSS}	Drain-Source Leakage Current (T=25°C)	$V_{DS}=-30V, V_{GS}=0V$	-	-	-1	μA
	Drain-Source Leakage Current (T=70°C)	$V_{DS}=-24V, V_{GS}=0V$	-	-	-25	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 20V$	-	-	±100	nA
Q_g	Total Gate Charge ²	$I_D=-4A$	-	6	10	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=-28V$	-	1	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=-4.5V$	-	4	-	nC
$t_{d(on)}$	Turn-on Delay Time ²	$V_{DS}=-15V$	-	8	-	ns
t_r	Rise Time	$I_D=-1A$	-	7	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega, V_{GS}=-10V$	-	20	-	ns
t_f	Fall Time	$R_D=15\Omega$	-	4	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	410	660	pF
C_{oss}	Output Capacitance	$V_{DS}=-25V$	-	95	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0MHz$	-	70	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_S=-1.7A, V_{GS}=0V$	-	-	-1.2	V
t_{rr}	Reverse Recovery Time	$I_S=-4A, V_{GS}=0V$	-	21	-	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=-100A/\mu s$	-	16	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 3.Surface mounted on 1 in² copper pad of FR4 board, $t \leq 10sec$; 90°C/W when mounted on min. copper pad.
- 4.Starting $T_j=25^\circ C$, $V_{DD}=25V$, $L=1mH$, $R_G=25\Omega$



AP4513GD

N-Channel

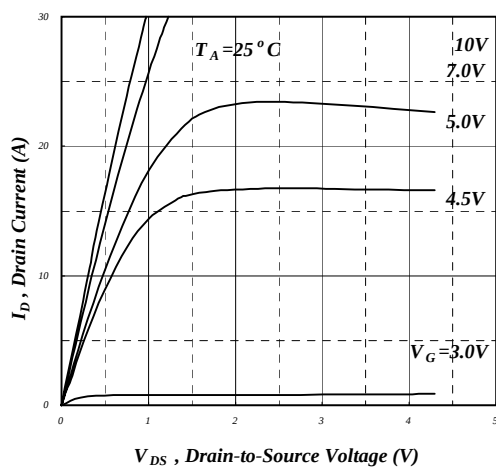


Fig 1. Typical Output Characteristics

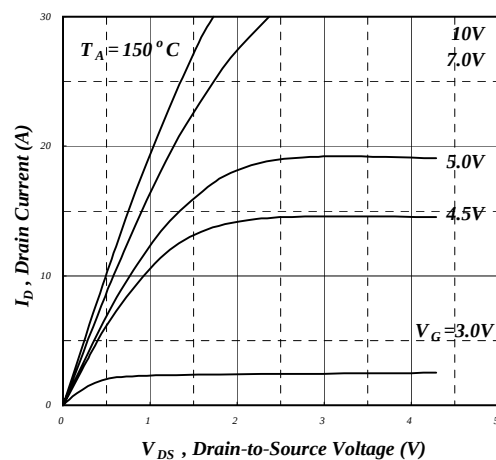


Fig 2. Typical Output Characteristics

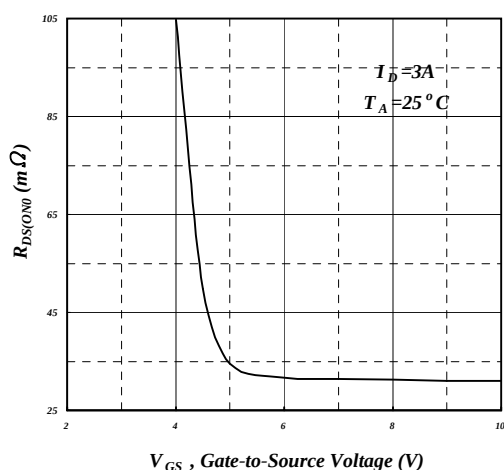


Fig 3. On-Resistance v.s. Gate Voltage

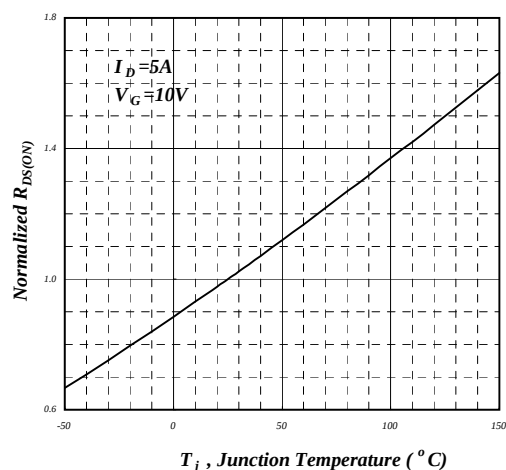


Fig 4. Normalized On-Resistance v.s. Junction Temperature

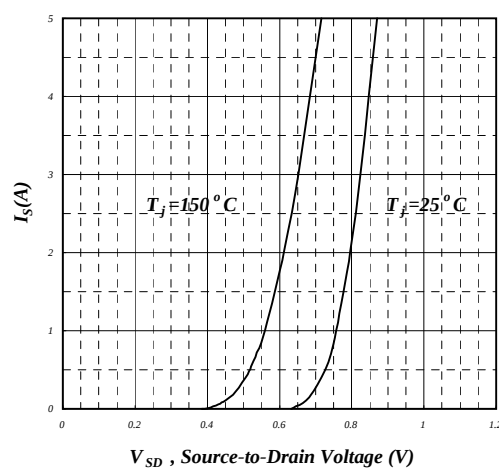


Fig 5. Forward Characteristic of Reverse Diode

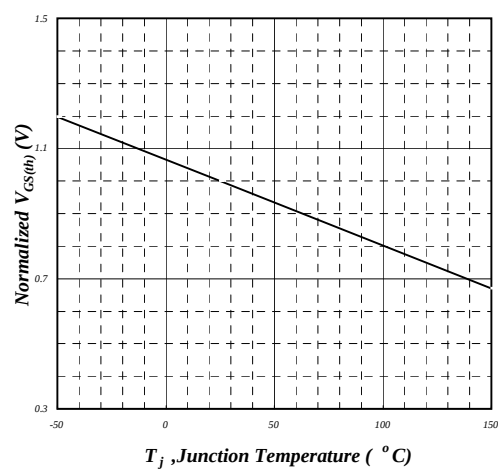


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



N-Channel

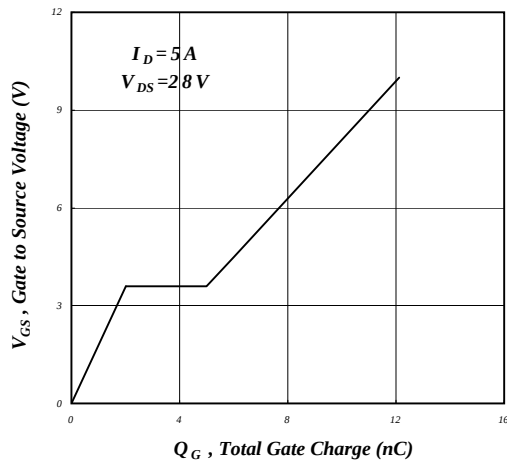


Fig 7. Gate Charge Characteristics

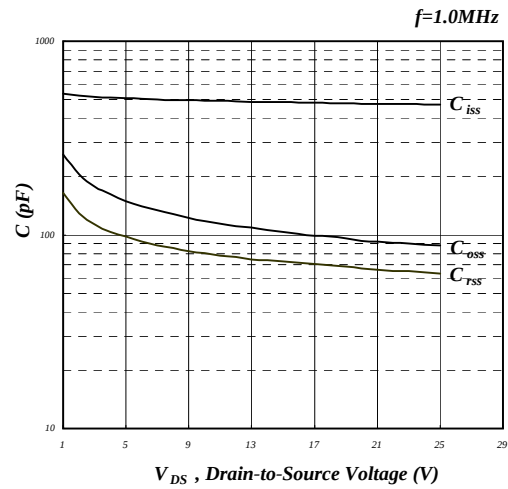


Fig 8. Typical Capacitance Characteristics

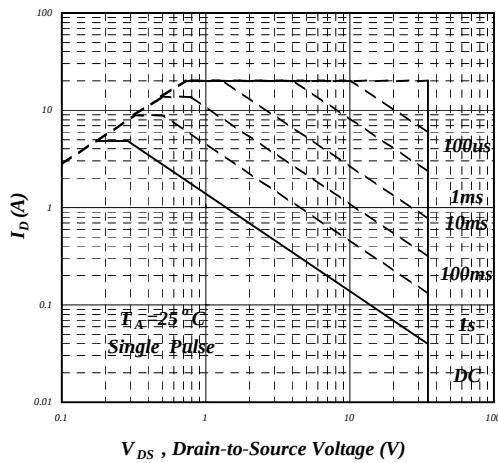


Fig 9. Maximum Safe Operating Area

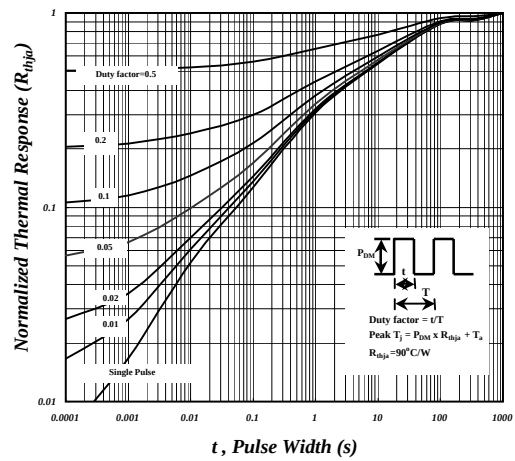


Fig 10. Effective Transient Thermal Impedance

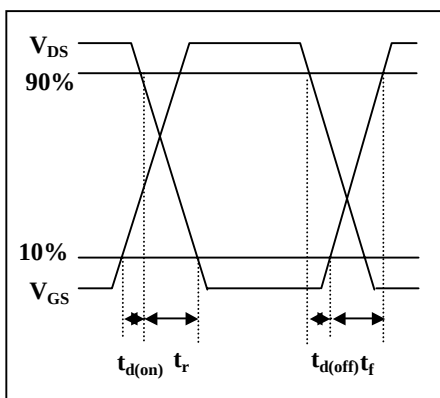


Fig 11. Switching Time Waveform

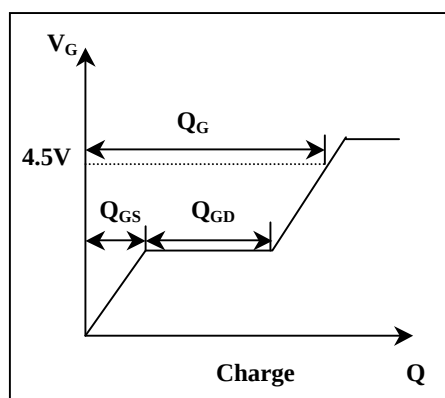


Fig 12. Gate Charge Waveform



AP4513GD

P-Channel

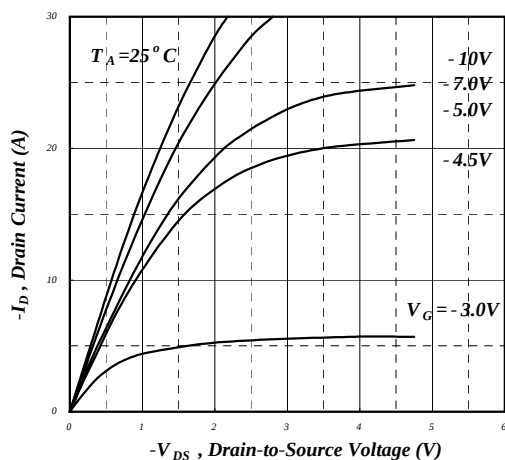


Fig 1. Typical Output Characteristics

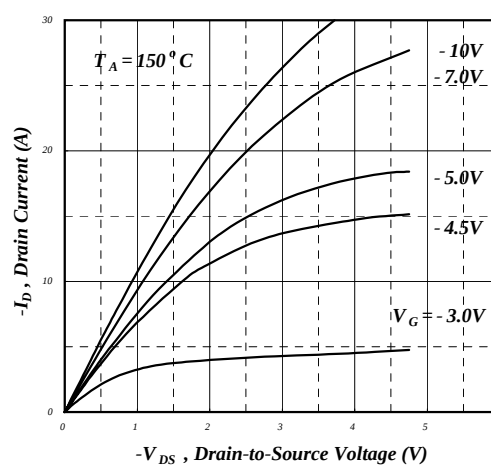


Fig 2. Typical Output Characteristics

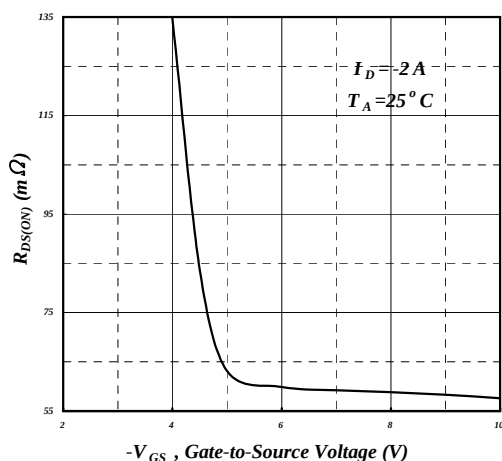


Fig 3. On-Resistance v.s. Gate Voltage

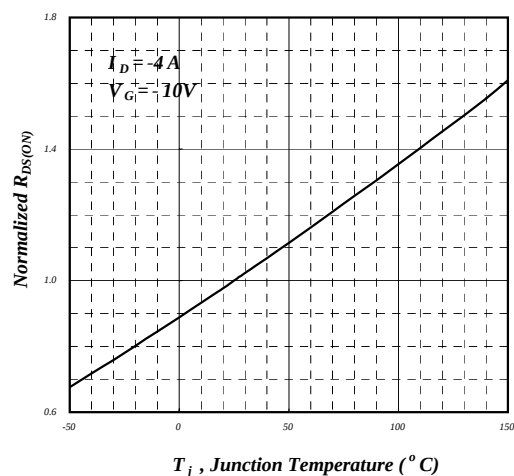


Fig 4. Normalized On-Resistance
v.s. Junction Temperature

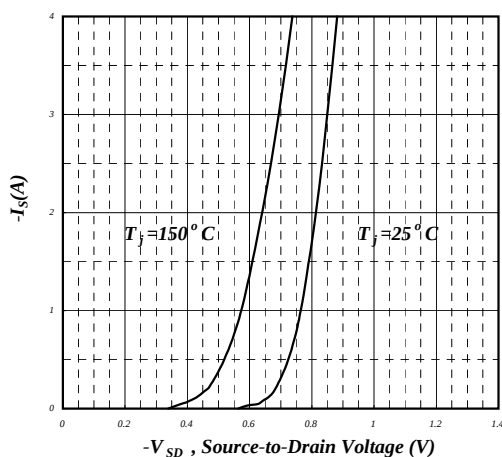


Fig 5. Forward Characteristic of
Reverse Diode

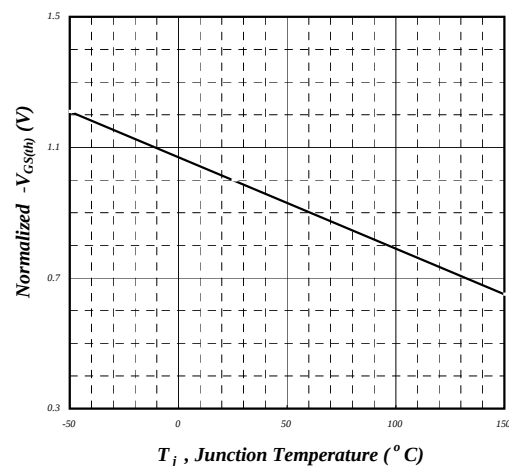


Fig 6. Gate Threshold Voltage v.s.
Junction Temperature



P-Channel

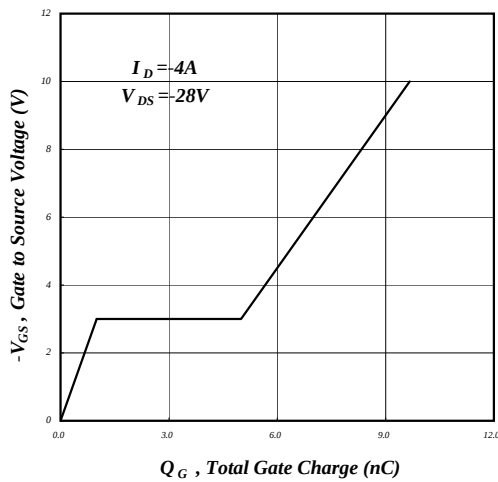


Fig 7. Gate Charge Characteristics

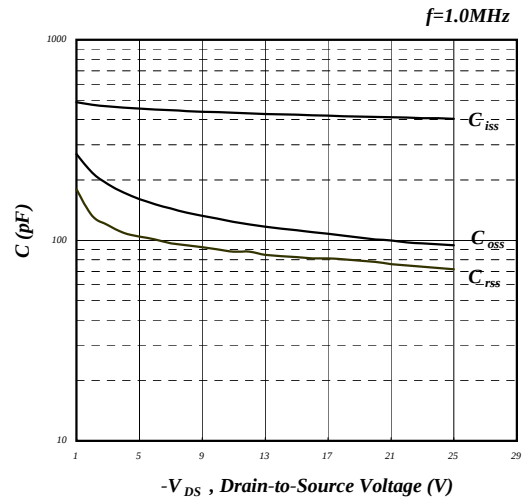


Fig 8. Typical Capacitance Characteristics

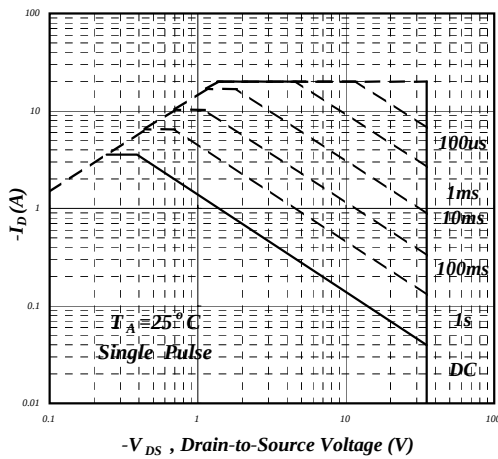


Fig 9. Maximum Safe Operating Area

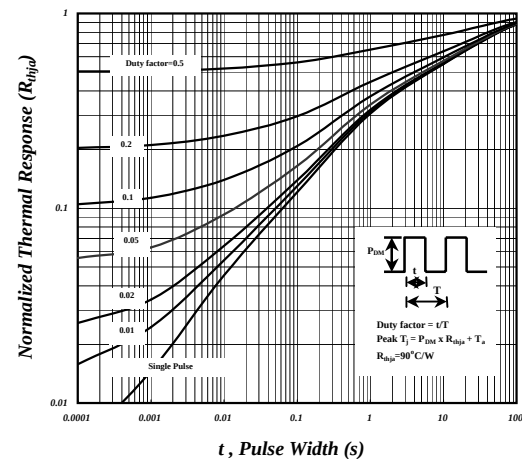


Fig 10. Effective Transient Thermal Impedance

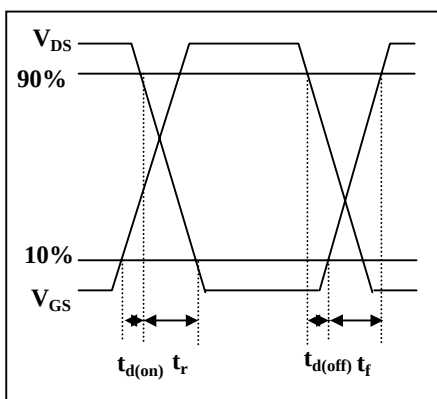


Fig 11. Switching Time Waveform

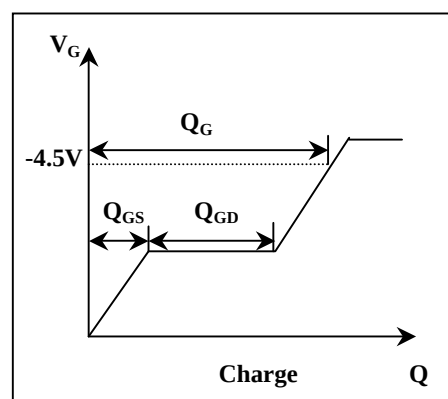


Fig 12. Gate Charge Waveform